
FINAL PRODUCT/PROCESS CHANGE NOTIFICATION

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14 Jan 2008

SUBJECT: ON Semiconductor Final Product/Process Change Notification #16090

TITLE: FPCN for Qualification of UDFN/UQFN 0.5mm Package Thickness (1.0x1.2mm to 3.0x3.0mm) at ON Semiconductor SBN and at UTAC (Bangkok, Thailand)

PROPOSED FIRST SHIP DATE: 14 Apr 2008

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Assembly & Test

AFFECTED PRODUCT DIVISION(S): Digital Consumer Group, Computing Products Group

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Todd Manes <todd.manes@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or Mark Wasilewski <m.wasilewski@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This is a Final Product Change Notice (FPCN) notifying customers that the changes described in PCN 15676 (which can be found at www.onsemi.com), have been completed for the listed devices.

There will be no changes in device functionality, case outline, or footprint. Reliability will continue to meet or exceed ON Semiconductor’s highest standards. Upon expiration of this FPCN, all UDFN/UQFN (1.0x1.2mm to 3.0x3.0mm) 0.55mm max thickness devices will be sourced from both the ON Semiconductor Seremban (Malaysia) facility and the UTAC facility located in Bangkok, Thailand. Any new devices/derivatives packaged on the same platforms released after publication of this inclusive FPCN will be qualified for assembly in both locations.

Final Product/Process Change Notification #16090

RELIABILITY DATA SUMMARY:

Reliability Test Results:

Test	Conditions	Results
PC+UHAST	TA=131C, 96 hrs	0/240 (3 lots of 80 each)
PC+TC	TA=-65C to +150C, 1000 cyc	0/240 (3 lots of 80 each)
PC+SAT	MSL1, 260C	0/30 (3 lots of 10 each)
HTOL	TA=135C, 1008 hrs	0/240 (3 lots of 80 each)
PC+HAST	TA=131C, 96 hrs	0/240 (3 lots of 80 each)

ELECTRICAL CHARACTERISTIC SUMMARY:

All products' performance meets current datasheet specifications.

CHANGED PART IDENTIFICATION:

Products manufactured after the FPCN expiration date can be manufactured at either ON Semiconductor Seremban or at UTAC Thailand. Assembly location code will be maintained for traceability.

Final Product/Process Change Notification #16090

AFFECTED DEVICE LIST

NCP1521BMUTBG
NCP1522BMUTBG
NCP1526MUTXG
NCP2820MUTBG
NCP360MUTBG
NCP360MUTXG
NCP361MUTBG
NCS2200AMUT1G
NCS2220AMUT1G
NLAS5113MUTBG
NLAS5213AMUTAG
NLAS5213BMUTAG
NLAS5224MUTBG
NLAS6233MUTBG
NLAS6234MUTBG
NLAS7213MUTAG
NLAS7213MUTBG
NLAS7222AMUTBG
NLAS7222BMUTBG
NLAS7222CMUTBG
NLAS7223BMUTAG
NLAS7223BMUTBG
NLAS7223CMUTAG
NLAS7223CMUTBG
NLAS8252MUTBG
NLMD5820MUTAG
NUF3102MUTAG
NUF4000MUT2G
NUF4010MUT2G
NUF4152MUT2G
NUF6005MUT2G
NUF6010MUT2G
NUF8000MUT2G
NUF8010MUT2G
NUF8152MUT2G
NUP5150MUTBG
NUP8011MUTAG